

low frequency delivery path on said package unit and to said first node, and said high frequency reception path coupled to said high frequency delivery path on said package unit and to said first node.

10. (Amended) A power delivery system comprising:

a circuit board including a power supply device to provide a voltage signal;

a package coupled to said board so as to receive said voltage signal and having a first delivery path to provide a first output voltage signal and a second delivery path to provide a second output voltage signal; and

a die coupled to said package so as to receive said first output voltage signal at a first node and to receive said second output voltage signal at a second node, said die having a capacitive element and a component coupled in parallel between said first node and a third node so as to receive voltage signals from said package, wherein said power delivery system includes a resistive element provided between said second node and said first node.

14. (Amended) A power delivery system comprising:

a package having a first node, a second node, a third node, a fourth node and a fifth node, said package having a first delivery path between said first node and said third node, said package further having a second delivery path between said second node and said fourth node; and

a die having a sixth node, a seventh node and an eighth node, said sixth node coupled to said third node of said package, said seventh node coupled to said fourth node of said package, said eighth node coupled to said fifth node of said package, said die including a component provided between said seventh node and said eighth node and a capacitive element provided between said sixth node and said eighth node, wherein said power delivery